

RESIN MOLDED PRODUCT MANUFACTURING APPARATUS, RESIN
MOLDING SYSTEM, AND RESIN MOLDED PRODUCT MANUFACTURING
METHOD

5 ABSTRACT OF THE DISCLOSURE

There is provided a resin molded product manufacturing apparatus, resin
molding system, and resin molded product manufacturing method that can reduce
variation in thickness of a resin molded product. The resin molded product
manufacturing apparatus includes: a first platen; a first mold chase holder provided on
10 the first platen and configured to hold a first mold chase; a second platen spaced from
the first platen and facing the first platen; and a second mold chase holder provided on
the second platen and configured to hold a second mold chase. A notch is provided on
a side of the first platen closer to the second platen. A thickness of the first platen at
an outer end portion of the notch is smaller than a thickness of the first platen at an
15 inner end portion of the notch.

FIG. 1